

U.S. Patent Application of Tokmulin et al.  
Serial No.: 08/860,763  
Art Unit: 1763

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**PRELIMINARY AMENDMENT**

Simultaneously with the filing of a Continued Prosecution Application (CPA) herewith, and in response to the final Office Action in the parent application, mailed April 25, 2000, please amend the above identified application as follows.

**IN THE CLAIMS:**

Please cancel claim 4, without prejudice, add claim 14 and amend claims 2 and 5 as follows. (Note that the text of claims 2 and 5 given below do not show additions and deletions; Attachment A to this Amendment gives this text again, with additions and deletions shown.)

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2. (Amended) A device for treating wafers with a plasma jet, comprising a plasma jet generator; gas supplying means; a set of holders for wafers to be treated, said holders having a drive for effecting angular displacement thereof and for facing a generator plasma jet; each of the holders being made in the form of a horizontal platform mounted for rotation about an axis passing through a geometric center thereof and

perpendicular to a plane of said platform; said plasma jet and wafer  
holders being displaced with respect to each other and may be in or out of  
contact with each other, said plasma jet generator being located such that  
a plasma jet is directed upwardly in respect of a plane of said horizontal  
platforms of said wafer holders; and cooling means associated with each  
horizontal platform in fluid flow communication with said gas supplying  
means and located such that resulting gas flows permit the positioning of  
the platform near a holder and improve cooling of individual areas over the  
wafer surfaces while avoiding the need to provide additional cooling of  
said plasma generator due to natural convection of the hot gases.

5. (Amended) A device as defined in claim 14, wherein said closed  
C2 chamber is provided with a window in which a movable shutter is mounted,  
said manipulator being located to contact with said storage devices  
directly and with said wafer holder indirectly, through the chamber window.

14. (New) A device for treating wafers with a plasma jet, comprising  
C3 a plasma jet generator; gas supplying means; a set of holders for wafers

to be treated, said holders having a drive for effecting angular displacement thereof and for facing a generator plasma jet; each of the holders being made in the form of a horizontal platform mounted for rotation about an axis passing through a geometric center thereof and perpendicular to a plane of said platform; said plasma jet and wafer holders being displaced with respect to each other and may be in or out of contact with each other, said plasma jet generator being located such that a plasma jet is directed upwardly in respect of a plane of said horizontal platforms of said wafer holders; cooling means associated with each horizontal platform in fluid flow communication with said gas supplying means and located such that resulting gas flows permit the positioning of the platform near a holder and improve cooling of individual areas over the wafer surfaces while avoiding the need to provide additional cooling of said plasma generator due to natural convection of the hot gases; a manipulator; storage devices for the wafers to be treated; and a closed chamber having a gas exchange system with the wafer holders and a